

12-24-2002

Atty. Docket No. FIS920020197US1



J FORM COVER SHEET
S ONLY

To the Honorable
copy thereof.

102320149

Remarks: Please record the attached original documents or

1. Name of Conveying party(ies): **Sandra G. Malhotra, Andrew H. Simon**

3. Nature of Conveyance: **Assignment**

Execution Date: **12/06/02, 12/06/02.**

2. Name & address of receiving party(ies)

Name: **International Business Machines Corporation**

Street

Address: **New Orchard Road**

City: **Armonk** State: **New York** ZIP: **10504**

JC986 U.S. PTO
10/31/02
12/11/02

4. Application number(s) or patent number(s):

Title of Application: **A METHOD FOR DEPOSITING A METAL LAYER ON A SEMICONDUCTOR INTERCONNECT STRUCTURE**

If this document is being filed together with a new application, the execution date of the application is: **12/06/02, 12/06/02**

A. Patent Application No(s).

Docket No.

Serial No.

B. Patent No(s)

Additional numbers attached? Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Ira D. Blecker**

Street Address:

32074
PATENT TRADEMARK OFFICE

IBM Corporation

Intellectual Property Law Dept.

Dept. 18G/Bldg. 300-482

2070 Route 52

Hopewell Junction, NY 12533-6531

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

Enclosed

X Authorized to be charged to deposit account

8. Deposit A/C no.: **09-0458 (FI-566)**
(Attach duplicate copy of this page if paying by deposit account)

12/23/2002 TDIAZI 00000038 090458 10318605

01 FC:8021

40.00 CH

DO NOT USE THIS SPACE

9. Statement of signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ira D. Blecker, Reg. No. 29,894

Name of Person Signing

Telephone No. (845) 894-2580

Signature

Date

Total number of pages, including cover sheet, attachments, and document 2

Express Mail No. **EU702259826US**

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to: UNITED STATES PATENT & TRADEMARK OFFICE, PO BOX 2327, ARLINGTON, VA 22202. Applicant and/or Attorney requests the date of deposit as the filing date.

December 11, 2002

DATE OF DEPOSIT

KAREN CINQ-MARS

SIGNATURE AND DATE

PATENT
REEL: 013592 FRAME: 0990

ASSIGNMENT

WHEREAS, we

(1) Sandra G. Malhotra	of Beacon
County of Dutchess	State of New York
and	
(2) Andrew H. Simon	of Fishkill
County of Dutchess	State of New York

have invented certain improvements in

A METHOD FOR DEPOSITING A METAL LAYER ON A SEMICONDUCTOR INTERCONNECT STRUCTURE

and executed a United States patent application therefor on:
(dates that Inventors signed the declaration)

(1) 12/6/2002, and (2) 12/6/2002.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire, right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed

(1) at East Fishkill, NY
on 12/6/2002,

Sandra G. Malhotra
Sandra G. Malhotra

(2) at East Fishkill, NY
on 12/6/2002,

Andrew H. Simon
Andrew H. Simon